



2018

media data

why professionals read

Asia Electronics Industry

- Covers vital and fundamental areas of electronics
- Penetrates the most critical markets in Asia
- Provides timely information to professionals
- Evolves with the industry in shaping future landscape

AEI. Keeps you informed. Helps your business grow.

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editorial calendar

| Issue | Date of issue | Ad closing date | Ad data closing date | Featured articles | Featured articles Exhibition Special & Supplement | Distributed Exhibitions |
|-----------------|---------------|-----------------|----------------------|---|--|--|
| January issue | 12/28 | 12/5 | 12/15 | <ul style="list-style-type: none"> •Power Electronics •Smart Energy | CES 2018 Energy Storage India 2018 | CES 2018 Jan.9-12 (Las Vegas) Energy Storage India 2018 Jan.11-12 (New Delhi) |
| February issue | 1/30 | 1/9 | 1/19 | <ul style="list-style-type: none"> •Test & Measurement Instruments for IoT & 5G •High-functional modules | SEMICON Korea 2018 | SEMICON Korea 2018 Jan.31-Feb.2 (Seoul) |
| March issue | 2/27 | 2/5 | 2/15 | <ul style="list-style-type: none"> •Industrial Robot & Sensor •SMT components/parts in wiring boards •Semiconductor Manufacturing Equipment and Electronic Materials | SEMICON China 2018 electronica & productronica China 2018 Japanese manufacturing equipment manufacturers Chinese edition, spring issue | SEMICON China 2018 Mar.14-16(Shanghai) electronica & productronica China 2018 Mar.14-16(Shanghai) |
| April issue | 3/29 | 3/7 | 3/15 | <ul style="list-style-type: none"> •IoT & Industry 4.0 •Key Devices of Car Electronics | NEPCON Korea 2018 NEPCON China 2018 | NEPCON Korea 2018 Apr.11-13 (Seoul) NEPCON China 2018 Apr.24-26 (Shanghai) |
| May issue | 4/27 | 4/6 | 4/16 | <ul style="list-style-type: none"> •MEMS, Sensors & Module •Medical/Nursing/Health Care and ICT | Inatronics 2018 PCB EXPO Thailand 2018 | Inatronics 2018 May.3-5 (Jakarta) PCB EXPO Thailand 2018 May.10-12 (Bangkok) Intermach & Subcon Thailand 2018 May.16-19 (Bangkok) |
| June issue | 5/28 | 5/8 | 5/16 | <ul style="list-style-type: none"> •CPS & IoT •Wireless Power Transmission •IoT & Connector Technology | Computex Taipei 2018 NEPCON Thailand 2018 Special:eNews Letter Communic Asia 2018 | Computex Taipei 2018 Jun.5-9 (Taipei) NEPCON Thailand 2018 Jun.20-23 (Bangkok) CES Asia 2018 Jun.13-15 (Shanghai) Communic Asia 2018 Jun.26-28(Singapore) |
| July issue | 6/28 | 6/8 | 6/15 | <ul style="list-style-type: none"> •EMC/Noise-suppression Components •PWB technologies | Cutting-Edge-Manufacturing Chinese Edition, summer issue | |
| August issue | 7/30 | 7/6 | 7/17 | <ul style="list-style-type: none"> •Component Technologies for Mobile Communications •Smart Factory Solutions | NEPCON South China 2018 Touch Taiwan 2018 | NEPCON South China 2018 Aug.28-30 (Shenzhen) Touch Taiwan 2018 Aug.29-31 (Taipei) |
| September issue | 8/29 | 8/6 | 8/15 | <ul style="list-style-type: none"> •Semiconductor Packaging Technologies •Green Technology •Advanced Technology of Touch Panel | SEMICON Taiwan 2018 electronica & productronica India 2018 | SEMICON Taiwan 2018 Sept.5-7 (Taipei) electronica & productronica India 2018 Sept.26-28(Bangalore) |
| October issue | 9/28 | 9/7 | 9/14 | <ul style="list-style-type: none"> •5G Network & Test Solutions •Printed, Flexible and Organic Electronics | TAITRONICS 2018 electronic Asia 2018 TPCA 2018 | NEPCON Vietnam 2017 Oct.11-13(Hanoi) TAITRONICS 2018 Oct.not yet (Taipei) electronic Asia 2018 Oct.13-16(Hong Kong) KES 2018 Oct.17-20(Seoul) TPCA 2018 Oct.24-26 (Taipei) |
| November issue | 10/29 | 10/5 | 10/15 | <ul style="list-style-type: none"> •EV Quick Charger Solution •Low-Ag Soldering Materials | electronica 2018 | electronica 2018 Nov.13-16 (Munchen) |
| December issue | 11/29 | 11/5 | 11/15 | <ul style="list-style-type: none"> •LOWA Techology & IoT •High-density Surface-Mounted Components •Components for Displays and New Materials | HKPCA 2018 Chinese edition Special edition on electronic components & measuring instruments | HKPCA & IPC 2018 Dec.not yet(Shenzhen) ELEXCON 2018 Dec.not yet (Shenzhen) |

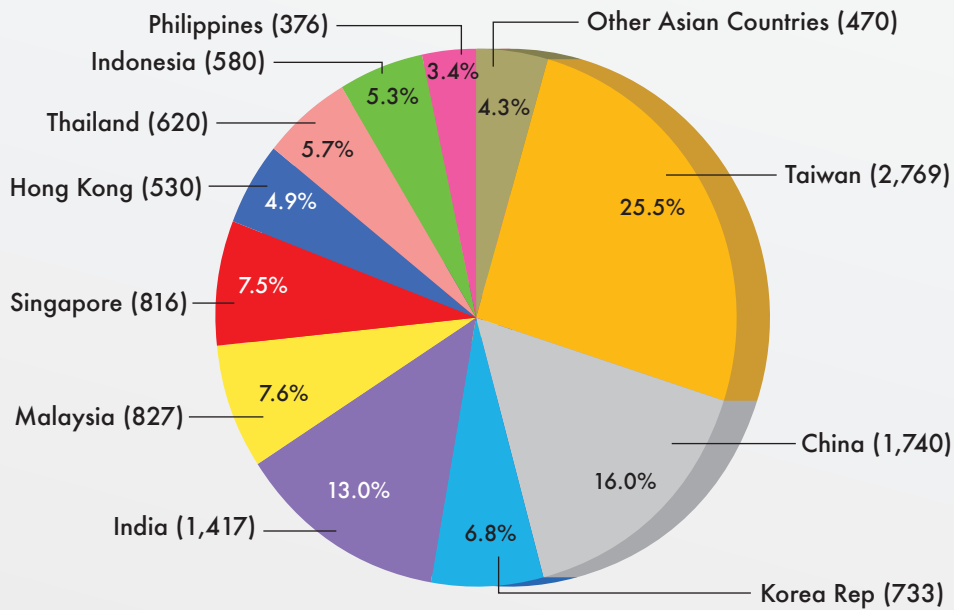


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Asia Electronics Industry
circulates to **11,000** professionals
in asian countries including china.

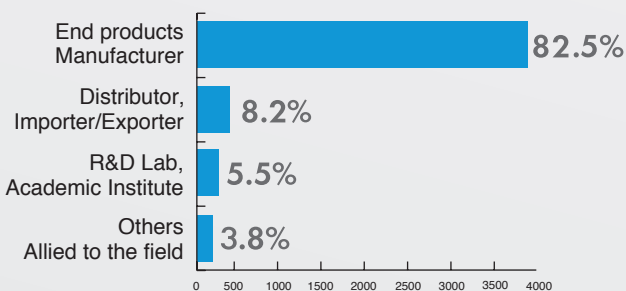
circulation

Regional Breakdown of Circulation

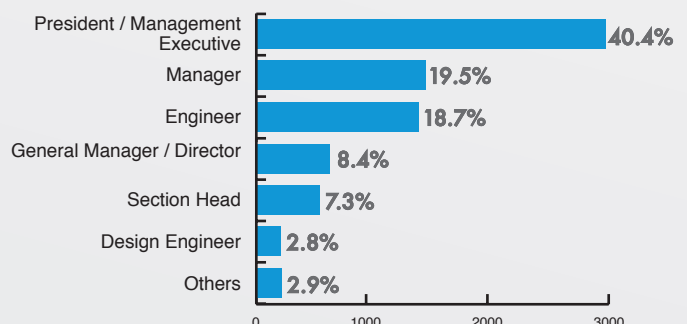


Analysis by:

type of business*

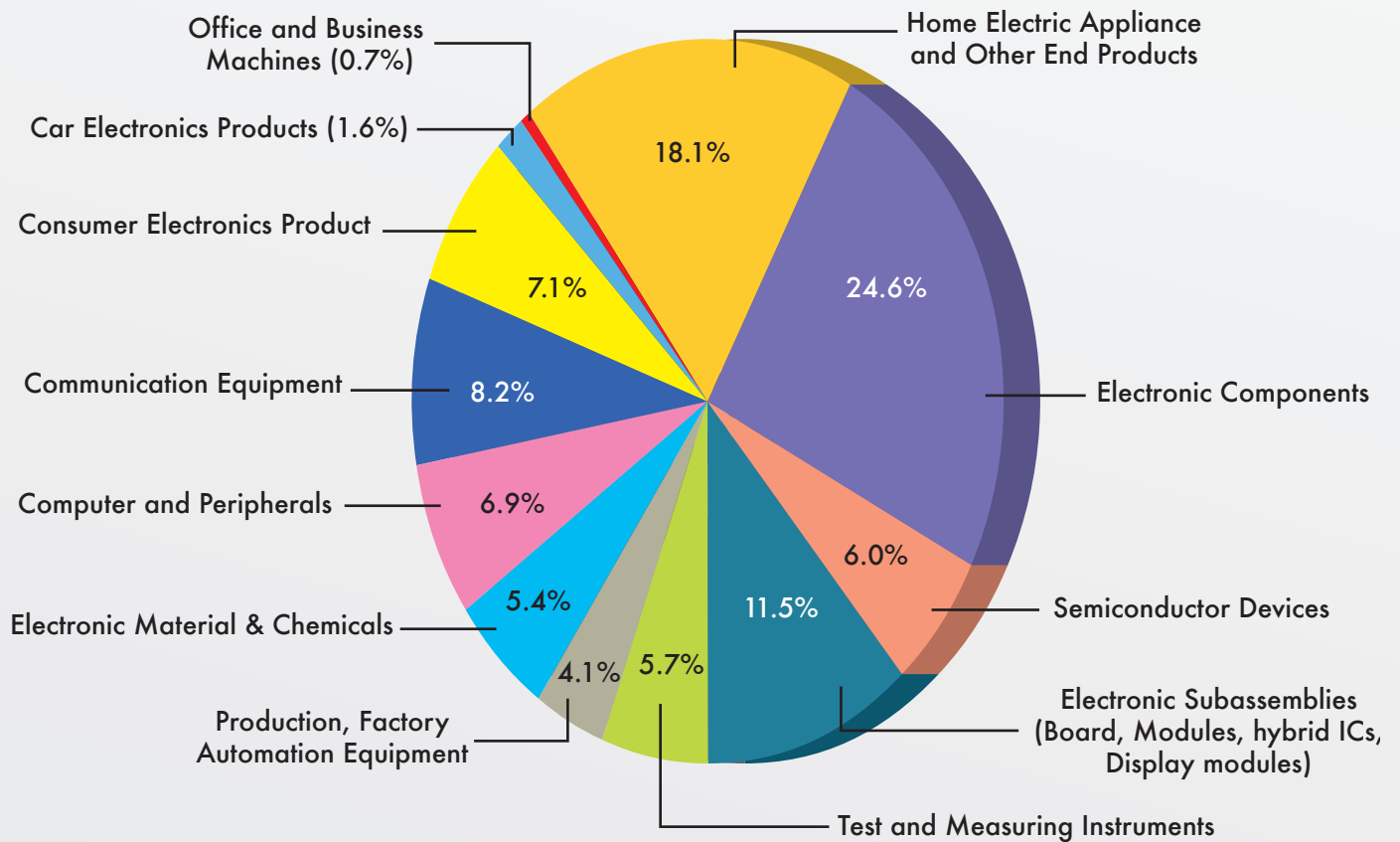


job title*



circulation

Breakdown by Primary End Product





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advertisements

Rates

| color | size | 12X | 6X | 3X |
|--------------------------|------------------|---------|---------|---------|
| Four-Color | Full page | \$1,850 | \$2,300 | \$2,800 |
| | 1/2 page | \$1,250 | \$1,600 | \$1,900 |
| | Full-page spread | \$2,900 | \$3,550 | \$3,950 |
| Two-Color | Full page | \$1,650 | \$2,100 | \$2,600 |
| | 1/2 page | \$1,050 | \$1,400 | \$1,700 |
| | Full-page spread | \$2,500 | \$3,150 | \$3,550 |
| Black & White | Full page | \$1,400 | \$1,850 | \$2,350 |
| | 1/2 page | \$800 | \$1,150 | \$1,450 |
| | Full-page spread | \$2,250 | \$2,900 | \$3,300 |



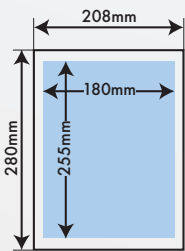
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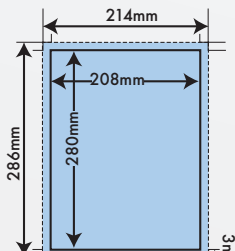
Mechanical Requirements

PUBLICATION TRIM SIZE: 208 x 280mm

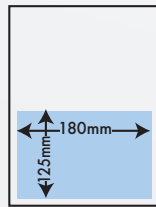
AD SIZES:



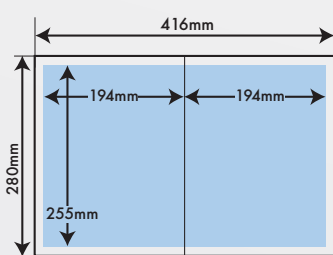
Full-page
Non-Bleed: (W x H)
180 x 255mm



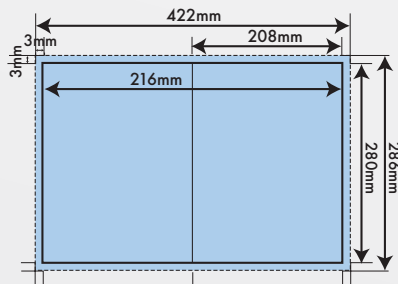
Full-page
Bleed: 3mm on all sides
(W x H) 214 x 286mm



Half page
Non-Bleed only:
(W x H) 180 x 125mm



Two-page spread
Non-Bleed: (W x H)
388 x 255mm



Two-page spread
Bleed: 3mm on all sides
(W x H) 422 x 286mm

DELIVERY METHOD

- FTP Files (preferred method)
- Burn all files to a CD or DVD and send to:

Cristian Canozo

Dempa Publications, Inc. - Regional Headquarters
Unit 2510 Herrera Tower, 98 V.A. Rufino St.
Salcedo Village, 1227 Makati City, Philippines

FORMAT

You may submit in digital format

ELECTRONIC Files (We accept files created using the following applications, using either Mac or PC)

- **Preferred format:** High-resolution press-ready PDF with crop marks and bleeds (for bleed ads)
- Adobe Illustrator CS or earlier
- Adobe Photoshop CS or earlier
 - File formats accepted are (for Illustrator and Photoshop) **.eps, .psd, .ai**
- Microsoft Word, PowerPoint or Microsoft Publisher files are not accepted. All files and placed graphics must use CMYK color profile and in a high-resolution format. (Minimum resolution of 300dpi and maximum resolution of 450dpi at 100% size)

Always include the following:

- Matchprint or color laser printout (exact size recommended)
- All placed graphics
- Both screen and printer fonts, Postscript 1 or 2
- Be sure to include all fonts from your placed graphics (i.e. .eps files) if fonts are not outlined.
- A printed listing of all files, fonts and graphics

For questions about the specifications, please e-mail or call:

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Tel: +63 2 845 0906 ext. 110

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 service

“You Are on the Cover”



- AEI advertisers whose contracts cover 12 or more full-pages per year are eligible for the cover position, featuring a photo of company executives, managers or employees at corporate facilities, public landmarks or trade shows.
- Along with the cover photo, a cover story featuring your corporate profile appears as the first article after the contents page.
- Your photo and profile will reach electronics professionals in the Asian region.
- Additionally, we provide you with up to 50 copies of the “You Are on the Cover” issue, for distribution to your branch offices and manufacturing plants. You can order even more copies for sales meetings and special distributions. Just contact the Dempa sales office nearest you.

COVER STORY

Shikoku Ltd. headquarter in Tokyo, Japan, consistently takes on challenges to make innovations in packaging technologies, targeting to become a leading company in the semiconductor bonding process.

SEMICON Taiwan 2017 was held from Sept. 11 to 15 at TWTC Nungshing Exhibition Center in Taipei, Taiwan. This year's 22nd edition drew 700 companies from 20 countries, including more than 50 Japanese manufacturers, and attended by more than 45,000 visitors. Exhibitors showcased their products, technologies, and materials to more than 1,800 visitors.

At the opening ceremony held on Sept. 11, Aji Masahiko, President and Chief Executive Officer of Semiconductor Equipment and Materials International (SEMI), said, "Taiwan is the world's largest consumer of semiconductor materials and manufacturing equipment. At this exhibition, exhibitors are showcasing cutting-edge technologies, equipment and materials. I expect that the exhibition provides a venue for active business negotiations and innovations."

At SEMICON Taiwan 2017, Shikoku showcased new products of UTC-5000SiC_u high-performance wafer bonder, which employs advanced packaging technology, and FPB-1wa NeoForce package bonder.

The UTC-5000SiC_u high-speed copper Cu wire bonder accommodates the wire bonding of fine-pitch devices to power devices, and supports bare Cu wire and palladium (Pd)-coat Cu wire. It has achieved high-speed bonding of 45mm²SiC_u on bare wire as an approved vendor of this model.

The FPB-1wa NeoForce multi-process package bonder accommodates various packaging processes, including

chip-to-wafer (C2W) solutions for the thermocompression bonding (TCB) process. Equipped with a function, which enables rapid switching in a short time, it has enabled the bonding of various packaging processes, including non-conductive paste (NCP), non-conductive film (NCF), thermal compression capillary underfill (TC-CUF), direct chip-connect (DCC), vertical collapse chip connection (C3) and fine-pitch level packaging (FPL) processes. In addition, it can support not only underfill, but also half-gold wire (HGA) substrates through short-time switching. Furthermore, it has realized high productivity and space saving as it equipped with a multi-head. Thus, it has many features that readily support customers' needs from development to mass production.

Referring to the recent semiconductor packaging equipment market, Takashi Nagano, President and Chief Executive Officer, Shikoku Ltd., says, "In the on-site market, including Taiwan and China, the demand for NAND flash increases

for large-capacity smart phones and servers has sharply increased since the latter half of last year. The demand for semiconductor has increased in various fields, including Internet of Things (IoT) and sensor-related fields, and the manufacturing equipment industry, including mainly fine-pitch wafer process equipment manufacturers, has grown drastically. In order to meet the trend, it is necessary to further advance semiconductor technologies.

Leading in our company's conditions in the Taiwanese market, packaging systems for leading-edge logic devices and memories have yet to take off. Logic that demands will pick up in Q4 and other. However, as previous companies are in short supply, we can secure delivery dates."

Referring to future business development, Nagano says, "At present, we are expanding our wafer bonder and wire bonder for logic devices and memories, by reducing functions and refinements. In particular, we are paying attention on further strengthening of flip-chip bonder. With memories, emphasis is put on NAND flash memories. We also focus effort on the automation of assembly process. We will work to reduce labor savings through the use of robots and establish solutions that incorporate artificial intelligence (AI) functions. We are also promoting cooperation with other companies to meet diversifying demands. Japanese materials manufacturers have advanced technologies, which is an encouraging trend. We intend to steadily implement these plans to achieve sales of ¥30 billion and operating profit of ¥3 billion in 2020 as we proceed in our medium-term plan."

- The advertiser provides us with a list of branch offices and manufacturing plants, plus the names of the key recipients. Dempa takes care of the rest.
- Volume discounts are available. For example, for more than 20 copies, 30% off the regular single-copy price (US\$18 × 0.7 or ¥1,500 × 0.7), plus shipping costs.



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contract and copy regulations

Dempa Publications, Inc.

1-11-15 Higashi Gotanda, Shinagawa-ku, Tokyo, 141-8715, Japan

1. Insertion instructions shall be supplied for every advertisement and shall clearly state the following information name of publication, name of advertiser, date to be inserted, size of advertisement, identification of advertisement (proof of ad to be furnished if possible) plus any special instructions such as bleed, color, etc.
2. No conditions, printed or otherwise, appearing on the space order, billing instruction or copy instructions which conflict with the publisher's stated policies will be binding on the publisher.
3. All advertising orders are accepted subject to the terms and provisions of the current rate card. Orders are accepted subject to change in rates upon notice from the publisher. However, orders may be cancelled at the time the change in rates becomes effective without incurring a short rate adjustment, provided the rate has been earned up to the date of cancellation.
4. Orders acceptable for not more than one year in advance.
5. A contract year, or twelve-month period, starts from the date of the first insertion. Twelve-month periods do not overlap; in other words, space counted in one contract period to determine the rate for that period, cannot be counted again toward determining the rate for the subsequent or past periods.
6. T. F. Contracts will be billed at rate earned through the previous twelve months or billed at rate earned through contract year period without incurring short rate, provided that the same frequency is maintained up to the time of cancellation.
7. Space orders wherever possible should specify a definite schedule of insertions, issues and sizes of space.
8. The forwarding of an order is construed as an acceptance of all the rates and conditions under which advertising is at the time sold.
9. The publisher reserves the right to void any contract unless the first insertion is used within three months from date thereof.
10. Verbal agreements are not recognized.
11. If more or fewer insertions are used within one year than specified in the order, charges will be adjusted in accordance with established rates.
12. Cancellation of space order forfeits the right to position protection.
13. The publisher reserves the right to give better position than specified in the order, at no increase in rate.
14. Advertiser and advertising agency agree to indemnify, defend, and save harmless the publisher from any and all liability for content (including text, illustrations, representatives, sketches, maps, trademarks, labels or other copyrighted matter) of advertisements printed, or the unauthorized use of any person's name or photograph arising from the publisher's reproduction and publishing of such advertisements pursuant to the advertiser's or agency's order. The publisher reserves the right to reject, discontinue or omit any advertising or any part thereof. This right shall not be deemed to have been waived by acceptance or actual use of any advertising matter.
15. Acceptance of advertising for any product or service is subject to investigation of the product or service, and of the claims made for it in the advertisement submitted for publication.
16. All advertising is subject to the publisher's approval. The publisher reserves the right to reject advertising which he feels is not in keeping with the publication's standard.
17. The publisher's liability for any error will not exceed the charge for the advertisement in question.
18. The publisher assumes no liability if for any reason it becomes necessary to omit an advertisement.
19. Publisher is not liable for delays in delivery and/or non-delivery in the event of Act of God, action by any governmental or quasi-governmental entity, fire, flood, insurrection, riot, explosion, embargo, strikes whether legal or illegal, labor or material shortage, transportation interruption of any kind, work slow-down, or any condition beyond the control of publisher affecting production or delivery in any manner.
20. Failure to make the order correspond in price or otherwise with the rate schedule is regarded only as a clerical error and publication is made and charged for upon the terms of the schedule in force without further notice.
21. The publisher reserves the right to limit the size of space to be occupied by an advertisement.
22. Two or more advertisers are not permitted to use space under the same contract.
23. Association advertising ordinarily takes the rate earned for space used by the association advertising alone. Individual members of associations cannot bulk their individual company space with the association space to earn a bulk rate for themselves.
24. Supplied inserts shall be charged regular black and white space rates plus additional production costs incurred. A charge lower or higher than actual black and white space rates would be considered price discrimination.
25. When change of copy, covered by an uncanceled insertion order, is not received by the closing date, copy run in the previous issue will be inserted.
26. Any deliberate attempt to simulate a publication's format is not permitted, and the publisher reserves the right to place the word "advertisement" with material which in the publisher's opinion resembles editorial matter.
27. Advertisements offering prizes, or contents of any nature, are accepted provided prior approval has been obtained from the Post Office at place of publication entry.
28. Requests for specified position at R. O. P. rates are given consideration but no guarantee is made unless the position premium has been provided for in the contract.
29. An advertiser requesting that a standard full page plate be printed without the name and page number appearing on the page shall be charged a premium.
30. No allowance is made to advertisers for furnishing complete plates, text and illustrations for their advertisements.
31. Advertisements ordered set and not used will be charged for composition.
32. Publisher reserves right to hold advertiser and/or its advertising agency jointly and severally liable for such monies as are due and payable to the publisher.



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